


- 1 Substrate: 0.0625" ± 0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- 2 Substrate: 0.125" ± 0.007" FR4/G10 or equivalent high temp material. Non-clad

- 3 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- 4 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.).

Description: SSOP Carrier Adaptor
56 position SSOP open top ZIF socket to 56 position SSOP leadless surface mountable foot.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

	CA-SO56B-L-Z-01 Drawing			Status: Released	Scale 2:1	Rev: A
	© 1999 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com			Drawing: E Smolentseva		Date: 7/20/99
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